

IEEE P802.3df Task Force – Logic Ad hoc

26 April 2023 Ad hoc Electronic Teleconference Meeting

Approved Meeting Minutes, Prepared by Mark Gustlin

Meeting called to order at 10:01 am (all times ET) by Mark Gustlin, who was chairing the meeting.

Chair noted that individuals should fill out IMAT information for attendance.

Presentation #1

Agenda and General Information

Presenter:

Mark Gustlin

URL

https://www.ieee802.org/3/df/public/adhoc/logic/23_0426/agenda.pdf

The chair asked if there were any modifications for the agenda (See slide #2) – there were none.

There were no other objections to the approval of the agenda, and it was considered approved by unanimous consent.

The chair asked if there were any modifications for the meeting minutes from the June 30th meeting – there were none.

The chair noted an email had been sent out to the reflector reminding individuals to review the following IEEE SA policies-

- IEEE SA Participation Policy
- IEEE SA Copyright Policy
- IEEE SA Patent Policy

Chair asked if anyone needed any of these policies reviewed in-depth. There were no requests.

Presentation #2

800GbE Logic Skew

Presenter

Mike Li

URL

https://www.ieee802.org/3/df/public/adhoc/logic/23_0426/li_3df_logic_230426a.pdf

Presentation #3

Thoughts on PCS, PMA Skew Limits for 800 Gb/s Ethernet

Presenter

Angela Lambert

URL

https://www.ieee802.org/3/df/public/adhoc/logic/23_0426/lambert_3df_logic_230426.pdf

Meeting adjourned at 10:28am.

Attendees (per IMAT)

Name	Employer	Affiliation
Chen, Chan	Self Employed	Self Employed
Choudhury, Golam	OFS	OFS
Dawe, Piers J G	NVIDIA	Nvidia
Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Heck, Howard	Intel	Intel

Jiang, Chendi	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Kim, Inho	MaxLinear	MaxLinear
Kimbara, Tatsuki		Hakusan; Optical Interconnect Products
Klempa, Michael	Alphawave Semi	Alphawave IP
Lambert, Angela	Corning Incorporated	Corning Incorporated
Lawson, Matthew	Cisco Systems, Inc.	Cisco Systems, Inc.
Li, Mike-Peng	Intel	Intel
Li, Pei-Rong	MediaTek Inc.	MediaTek Inc.
Liu, Karen	Nubis Communications	Nubis Communications
Lusted, Kent	Intel	Intel
		Malicoat Networking Solutions; SENKO
Malicoat, David	Malicoat Networking Solutions	Advanced Components
		Cadence Design Systems, Inc.
Marris, Arthur	Cadence Design Systems, Inc.	Inc.
Muller, Shimon	Enfabrica Corp.	Enfabrica
Muth, Karlheinz	Broadcom Corporation	Broadcom Corporation
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Palkert, Thomas	Macom, Samtec	Samtec-Macom
PARK, CHUL SOO	Juniper Networks Inc.	Juniper Networks, Inc.
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
		Huawei Technologies Co., Ltd
Ren, Hao	Huawei Technologies Co., Ltd	Ltd
Sakai, Toshiaki	Socionext Inc.	socionext
		Hewlett Packard Enterprise
Sikkink, Mark	Hewlett Packard Enterprise	Enterprise
Sommers, Scott	Molex LLC	Molex Incorporated
Sprague, Edward	Infinera Corporation	Infinera Corporation
		Huawei Technologies Co., Ltd
Stassar, Peter	Huawei Technologies Co., Ltd	Ltd
Summers, Robert		Broadcom Corporation
Tracy, Nathan	TE Connectivity	TE Connectivity
		China Mobile Communications Corporation (CMCC)
Wang, Haojie	China Mobile Communications Corporation (CMCC)	Corporation (CMCC)
Wu, Mau-Lin	MediaTek Inc.	MediaTek Inc.
Xu, Sunny	CommScope, Inc.	CommScope, Inc.
Yin, Shuang		Google